

ABSTRACT OF THE DISCLOSURE

A semiconductor chip including a bump projecting from a surface protective film thereof and a surface interconnection having a smaller height than the bump.

5 The surface interconnection may project from the surface protective film or may be flush with the surface protective film. The surface interconnection may be connected to the bump. The bump may include a peripheral bump configured as surrounding a device formation region of

10 the chip. The peripheral bump may be connected to the ground or a power source.